

SEMICONDUCTOR PACKAGE WITH CRACK-PREVENTING MEMBER

ABSTRACT

A semiconductor package with a crack-preventing member is proposed, in which a chip is mounted on a chip carrier by means of an adhesive and is electrically connected to the chip carrier. The crack-preventing member is formed at a proper position on the chip, and generates compression stress on the chip to sufficiently counteract tension stress produced from the chip carrier and adhesive in a molding process. This can effectively prevent the chip from cracking during molding, and thus improve the quality of fabricated products.

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